

Kulicke & Soffa Introduces New TeraCap™ Series Capillaries for Memory and Logic Applications

SINGAPORE--(BUSINESS WIRE)-- Kulicke & Soffa Industries, Inc. (NASDAQ: KLIC) ("Kulicke & Soffa", "K&S" or the "Company") today announced the introduction of TeraCap™ Series Capillaries for advanced memory and logic applications utilizing either Gold or Silver wire.

The TeraCap Series of capillaries is built on the Company's historic focus on advanced material development and deep-rooted application knowledge. This series of capillaries offers quality and cost benefits for advanced memory and logic devices applications.

Key highlights include:

- Greater Performance Consistency: The TeraCap's enhanced material properties enable uniform looping and high response during bonding.
- Yield Enhancement: Material and design improvements further extend the cost benefits of wire bonding by driving greater productivity and yield enhancements.
- Cost-of-Ownership Advantage: Improvements on Mean Time Between Assists (MTBA) and consistent bond quality drive meaningful cost benefits throughout the capillary's life.

Chan Pin Chong, Kulicke & Soffa's Vice President of the Wedge Bonders, Capillaries and Blades Business Lines, stated "The TeraCap Series for both Memory and Logic applications brings our process and capillaries know-how to the next level in supporting our customers' drive for both performance and cost of ownership. Aligned with our market leading wire bonding position, Teracap has demonstrated superior and consistent performance on logic and leading-node memory devices providing customers a new solution to further drive cost roadmaps."

The TeraCap Series of capillaries will debut during Kulicke & Soffa's seminar scheduled for January 27, 2016, in Seoul, Korea. Please contact your local sales and service representative for more information.

About Kulicke & Soffa

Kulicke & Soffa (NASDAQ: KLIC) is a global leader in the design and manufacture of semiconductor, LED and electronic assembly equipment. As a pioneer in this industry, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions and organic development, adding advanced packaging, advanced SMT, wedge bonding and a broader range of expendable tools to its core ball bonding products. Combined with its extensive expertise in process technology, K&S is well positioned to help customers meet the challenges of assembling the next-generation semiconductor and LED devices. (www.kns.com)

View source version

on businesswire.com: <http://www.businesswire.com/news/home/20160128005099/en/>

Kulicke & Soffa Industries, Inc.

Marilyn Sim

Public Relations

P: +65-6880-9309

F: +65-6880-9580

msim@kns.com

or

Joseph Elgindy

Investor Relations & Strategic Initiatives

P: +1-215-784-7500

P: +31-40-272-3016

F: +1-215-784-6180

investor@kns.com

<https://investor.kns.com/2016-01-28-Kulicke-Soffa-Introduces-New-TeraCap-TM-Series-Capillaries-for-Memory-and-Logic-Applications>